Abstract

The disclosure relates to an implant comprising a substrate (1), a first housing (2), wherein the first housing (2) is disposed on the substrate (1), an first electronic circuit (3) disposed on the substrate (1) inside the first housing (2), an electronic component (5) disposed on the substrate (1) outside the first housing (2), and a conductor track (6), wherein the conductor track (6) connects the first electronic circuit (3) to the electronic component (5). The conductor track (6) is embedded into the substrate (1) at least in sections in such a way that at least one section of the conductor track (6) is completely surrounded by the substrate (1) Furthermore, a method for creating an implant is disclosed.

FIG. 1